More info

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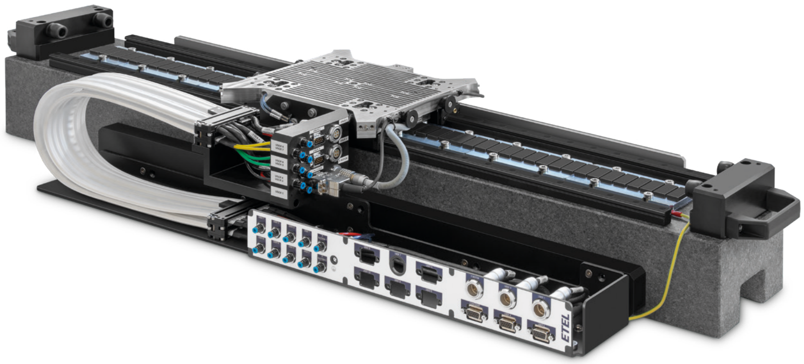

Bidirectional repeatability
±0.4 µm and ±0.25 arcsec

Position accuracy
±1 µm

Dynamics
Acceleration 1 g and speed 1 m/s

CHARON2

Stacked system/platform

ⓘ *For semiconductor applications*

CHARON2 is our most popular motion system platform. Through its robust and reliable stacked architecture, designed with modularity and scalability in mind, it is recognised as a cost effective entry point for many turn-key motion solutions.

The CHARON2 family comes in a multitude of different predefined configuration ranging from single X axis to complete 6 degree-of-freedom (DOF) motion system. The choice from our standard electronics makes the CHARON2 system scalable in performance to best meet the targeted specifications.
With over 3000 stages operating in the field, CHARON2 is addressing all semiconductor applications and many use cases of other markets, such as medical, pharmaceutical, or material science. Its position accuracy of ±1 µm level paired with excellent bidirectional repeatability and high dynamics are reached in an optimized footprint thanks to proprietary IP for motors, electronics and controlling, demonstrating ETEL's world-class innovation and expertise capabilities.

ISO2 CLEAN ROOM COMPATIBILITY
Suitable for controlled environments with stringent cleanliness requirements.

MICRON-LEVEL ACCURACY ACROSS THE ENTIRE WAFER
CHARON2 combined with the XYZ3™+ module provides 6-degree-of-freedom toolpoint control.
With ETEL electronics and system mapping, mechanical and stacking errors are compensated, keeping the substrate within ±1 µm over the full area and improving focus time and throughput—ideal for wafer inspection.

ENABLES WAFER HANDLING COARSE Z FUNCTION WITH THE Z3TM+ COMBINED MODULE
When combined with our Z3TM+ module, a 12 mm electric lifting mechanism can be used to handle wafer for loading and offloading.

BUILT-IN VACUUM SUPPLY AT CHUCK LEVEL
When used with our modules, Facilitates efficient operation by ensuring proper material handling.

- **Standard strokes of 365 x 355 mm and 475 x 410 mm**
- **Compact footprint and design suitable for space-limited applications**
- **Up to 30 kg payload**
- **Up to 6 degrees of freedom**

Ver. 1.1